

Title (en)
SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

Title (de)
LÖSUNGSMITTELUNTERSTÜTZTES POLIEREN VON VORUNTERFÜLLTEN MIT LÖTHÖCKERN BESTÜCKTEN WAFERN FÜR FLIPCHIP BONDING

Title (fr)
POLISSAGE AU SOLVANT DE PLAQUETTES A BOSSAGES DE SOUDURE ET A SOUS-REMPLISSAGE PREALABLE POUR UNE CONNEXION PAR BOSSAGES

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Application
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Abstract (en)
[origin: WO0233750A1] The present invention relates to a method for connecting an integrated circuit chip to a circuit substrate. The method includes the step of pre-applying adhesive directly to a bumped side of an integrated circuit chip. The method also includes the steps of removing portions of the adhesive from the tips of the solder bumps to expose a contact surface, and pressing the bumped side of the integrated circuit chip, which has previously been coated with adhesive, against the circuit substrate such that the bumps provide an electrical connection between the integrated circuit chip and the circuit substrate. The adhesive is removed from the tips of the solder bumps using a solvent assisted wiping action. The pre-applied adhesive on the chip forms a bond between the integrated circuit chip and the circuit substrate.

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H01L 23/485; **H01L 21/56**

IPC 8 full level
H01L 21/60 (2006.01); **H01L 21/56** (2006.01); **H01L 23/485** (2006.01)

CPC (source: EP KR)
H01L 21/563 (2013.01 - EP); **H01L 23/485** (2013.01 - KR); **H01L 24/10** (2013.01 - EP); **H01L 24/13** (2013.01 - EP); **H01L 24/29** (2013.01 - EP); **H01L 2224/1184** (2013.01 - EP); **H01L 2224/13** (2013.01 - EP); **H01L 2224/13099** (2013.01 - EP); **H01L 2224/16225** (2013.01 - EP); **H01L 2224/274** (2013.01 - EP); **H01L 2224/2784** (2013.01 - EP); **H01L 2224/29111** (2013.01 - EP); **H01L 2224/2919** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/73104** (2013.01 - EP); **H01L 2224/73203** (2013.01 - EP); **H01L 2224/73204** (2013.01 - EP); **H01L 2224/81101** (2013.01 - EP); **H01L 2224/83101** (2013.01 - EP); **H01L 2224/83191** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP); **H01L 2924/01015** (2013.01 - EP); **H01L 2924/01025** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/0105** (2013.01 - EP); **H01L 2924/01057** (2013.01 - EP); **H01L 2924/01075** (2013.01 - EP); **H01L 2924/01078** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/0132** (2013.01 - EP); **H01L 2924/01322** (2013.01 - EP); **H01L 2924/014** (2013.01 - EP); **H01L 2924/10253** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/15787** (2013.01 - EP); **H01L 2924/1579** (2013.01 - EP)

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